

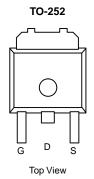
P-Channel 30 V (D-S) MOSFET

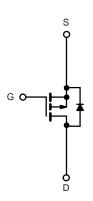
PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^a			
- 30	$0.009 \text{ at V}_{GS} = -10 \text{ V}$	± 80			
- 30	0.012 at V _{GS} = - 4.5 V	± 80			

FEATURES

• Compliant to RoHS Directive 2002/95/EC







P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
Parameter	Symbol	Limit	Unit			
Gate-Source Voltage	Gate-Source Voltage			V		
Continuous Drain Current (T _{.I} = 175 °C)	T _C = 25 °C	I _D	- 80 ^a	Α Α		
Continuous Diain Current (1 j = 175 C)	T _C = 125 °C		- 65			
Pulsed Drain Current	I _{DM}	- 240	Α			
Avalanche Current	I _{AR}	- 60				
Repetitive Avalanche Energy ^b	L = 0.1 mH	E _{AR}	180	mJ		
Power Dissipation	T _C = 25 °C (TO-220AB and TO-263)	Р	187 ^d	W		
rowei Dissipation	T _A = 25 °C (TO-263) ^c	P_{D}	3.75			
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Limit	Unit		
Junction-to-Ambient	PCB Mount (TO-263) ^c	В	40	°C/W		
Junction-to-Ambient	Free Air (TO-220AB)	R _{thJA}	62.5			
Junction-to-Case		R _{thJC}	0.8			

Notes:

- a. Package limited.
- b. Duty cycle \leq 1 %.
- c. When mounted on 1" square PCB (FR-4 material).
- d. See SOA curve for voltage derating.

^{*} Pb containing terminations are not RoHS compliant, exemptions may apply.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	•						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V, } I_{D} = -250 \mu\text{A}$	- 30				
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	- 1		- 3	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V _{DS} = - 30 V, V _{GS} = 0 V			- 1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 125 °C			- 50	- '	
		V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 175 °C			- 250		
On-State Drain Current ^a	I _{D(on)}	V _{DS} = - 5 V, V _{GS} = - 10 V	- 120			Α	
		V _{GS} = - 10 V, I _D = - 30 A		0.009		Ω	
Drain Course On State Registered	_D	V _{GS} = - 10 V, I _D = - 30 A, T _J = 125 °C			0.011		
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 10 V, I _D = - 30 A, T _J = 175 °C			0.013		
		V _{GS} = - 4.5 V, I _D = - 20 A		0.008	0.009		
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 75 A	20			S	
Dynamic ^b							
Input Capacitance	C _{iss}			9000		pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = -25 \text{ V}, f = 1 \text{ MHz}$		1565			
Reversen Transfer Capacitance	C _{rss}			715			
Total Gate Charge ^c	Qg			160	240		
Gate-Source Charge ^c	Q _{gs}	$V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -75 \text{ A}$		32		nC	
Gate-Drain Charge ^c	Q _{gd}			30		1	
Turn-On Delay Time ^c	t _{d(on)}			25	40		
Rise Time ^c	t _r	$V_{DD} = -15 \text{ V}, R_{L} = 0.2 \Omega$		225	360	20	
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong -75 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 2.5 \Omega$		150	240	ns	
Fall Time ^c	t _f			210	340		
Source-Drain Diode Ratings and Cha	racteristics ^b	(T _C = 25 °C)					
Continuous Current	I _S				- 80	۸	
Pulsed Current	I _{SM}				- 240	Α	
Forward Voltage ^a	V_{SD}	I _F = -75 A, V _{GS} = 0 V		- 1.2	- 1.5	V	
Reverse Recovery Time	t _{rr}			55	100	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = - 75 A, dl/dt = 100 A/μs		2.5	5	Α	
Reverse Recovery Charge	Q _{rr}			0.07	0.25	μC	

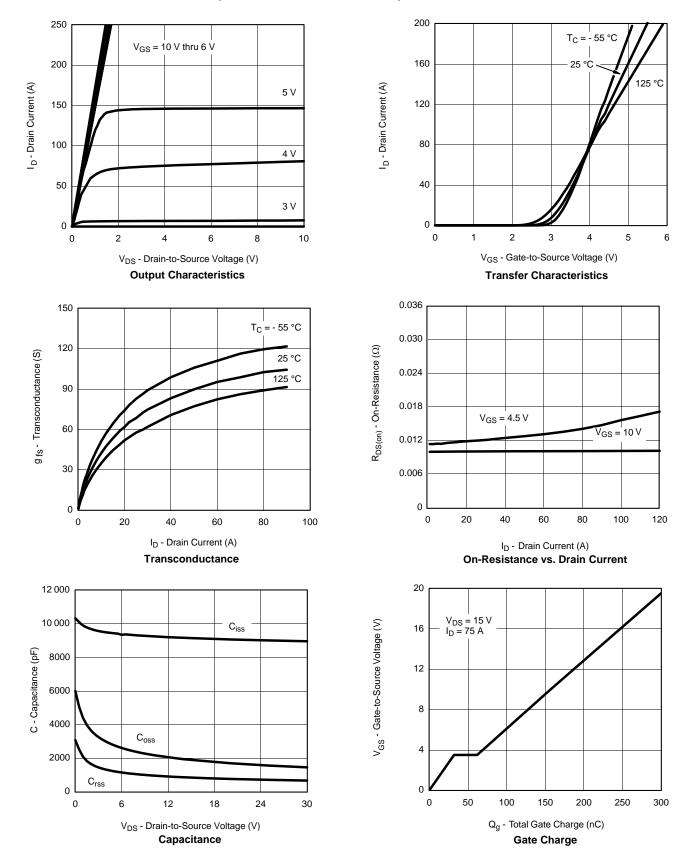
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

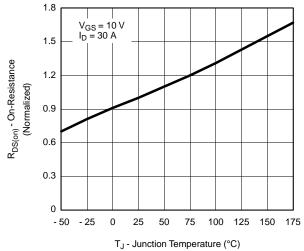


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

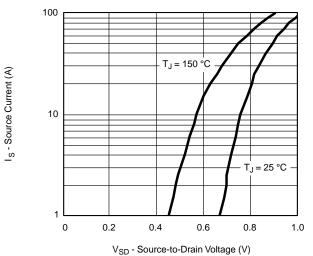




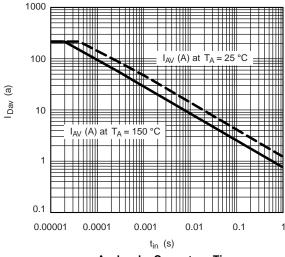
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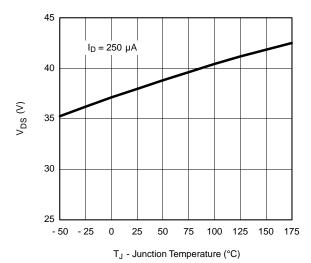
On-Resistance vs. Junction Temperature



Source-Drain Diode Forward Voltage



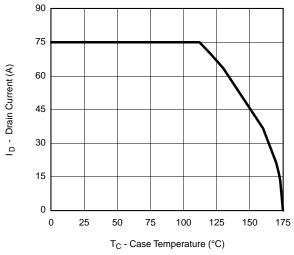
Avalanche Current vs. Time

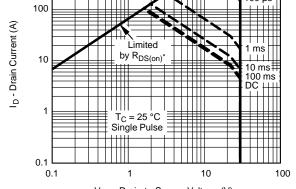


Drain Source Breakdown vs. Junction Temperature



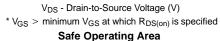
THERMAL RATINGS

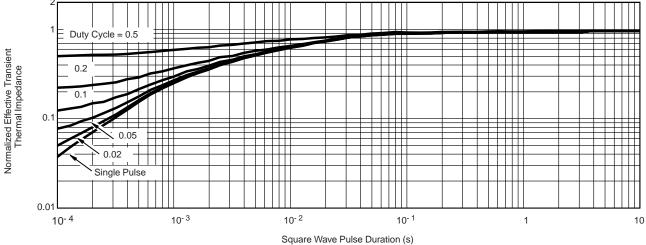




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Maximum Avalanche and Drain Current vs. Case Temperature

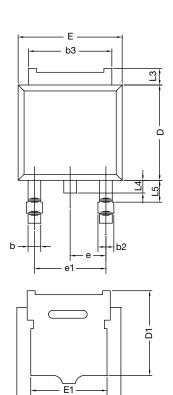


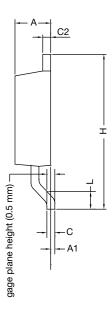


Normalized Thermal Transient Impedance, Junction-to-Case



TO-252AA CASE OUTLINE





	MILLIMETERS		INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.
А	2.18	2.38	0.086	0.094
A1	=.	0.127	-	0.005
b	0.64	0.88	0.025	0.035
b2	0.76	1.14	0.030	0.045
b3	4.95	5.46	0.195	0.215
С	0.46	0.61	0.018	0.024
C2	0.46	0.89	0.018	0.035
D	5.97	6.22	0.235	0.245
D1	5.21	-	0.205	-
E	6.35	6.73	0.250	0.265
E1	4.32	-	0.170	-
Н	9.40	10.41	0.370	0.410
е	2.28 BSC		0.090 BSC	
e1	4.56	BSC	0.180 BSC	
L	1.40	1.78	0.055	0.070
L3	0.89	1.27	0.035	0.050
L4	-	1.02	-	0.040
L5	1.14	1.52	0.045	0.060
ECN: X12-0247-Rev. M, 24-Dec-12				

ECN: X12-0247-Rev. M, 24-Dec-12 DWG: 5347

Note

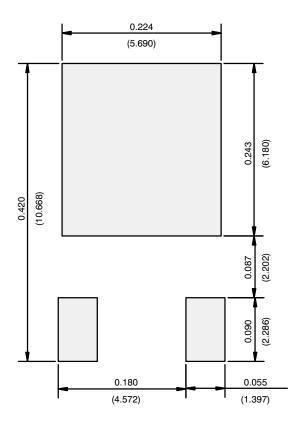
• Dimension L3 is for reference only.

E-mail: China@VBsemi TEL:86-755-83251052

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RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)



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